TOSHIBA Field Effect Transistor Silicon P Channel MOS Type (U-MOSIII)

TPCS8302

Lithium Ion Battery Applications
Notebook PC Applications
Portable Machines and Tools

- Small footprint due to small and thin package
- Low drain-source ON resistance: $RDS(ON) = 22 \text{ m}\Omega \text{ (typ.)}$
- High forward transfer admittance: $|Y_{fs}| = 12 \text{ S (typ.)}$
- Low leakage current: $I_{DSS} = -10 \mu A \text{ (max) (V}_{DS} = -20 \text{ V)}$
- Enhancement-mode: $V_{th} = -0.5 \sim -1.2 \text{ V (V}_{DS} = -10 \text{ V, I}_{D} = -200 \text{ }\mu\text{A})$

Maximum Ratings (Ta = 25°C)

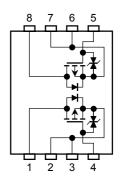
Char	acteristics	Symbol	Rating	Unit		
Drain-source vol	ce voltage V _{DSS} –20		-20	V		
Drain-gate voltag	ge (R _{GS} = 20 kΩ)	V _{DGR}	-20	V		
Gate-source volt	age	V _{GSS}	±12	V		
Drain current	DC (Note 1)	I _D	-5	Α		
Dialii Cuiteiii	Pulse (Note 1)	I _{DP}	-20	A		
Drain power dissipation (t = 10 s) (Note 2a)	Single-device operation (Note 3a)	P _{D (1)}	1.1			
	Single-device value at dual operation (Note 3b)	P _{D (2)}	0.75	W		
Drain power dissipation (t = 10 s) (Note 2b)	Single-device operation (Note 3a)	P _{D (1)}	0.6	W		
	Single-device value at dual operation (Note 3b)	P _{D (2)}	0.35			
Single pulse ava	oulse avalanche energy (Note 4) EAS 32.5		32.5	mJ		
Avalanche curre	nt	I _{AR} –5		I _{AR} –5		Α
Repetitive avalanche energy Single-device value at dual operation (Note 2a, 3b, 5)		E _{AR}	0.075	mJ		
Channel tempera	Channel temperature		150	°C		
Storage tempera	ture range	T _{stg}	-55~150	°C		

2-3R1E

Weight: 0.035 g (typ.)

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Circuit Configuration



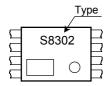
Note: (Note 1), (Note 2), (Note 3), (Note 4), (Note 5), please see next page.

This transistor is an electrostatic sensitive device. Please handle with caution.

Thermal Characteristics

Characteristics	Symbol	Max	Unit		
The second and interest of the combined	Single-device operation (Note 3a)	R _{th (ch-a) (1)}	114	°C/W	
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	Single-device value at dual operation (Note 3b)	R _{th (ch-a) (2)}	167		
Thermal resistance, channel to ambient	Single-device operation (Note 3a)	R _{th (ch-a) (1)}	208		
(t = 10 s) (Note 2b)	Single-device value at dual operation (Note 3b)	R _{th (ch-a) (2)}	357	°C/W	

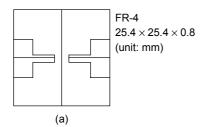
Marking (Note 6)



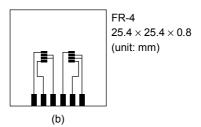
Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2:

a) Device mounted on a glass-epoxy board (a)



b) Device mounted on a glass-epoxy board (b)



Note 3:

- a) The power dissipation and thermal resistance values are shown for a single device (During single-device operation, power is only applied to one device.)
- b) The power dissipation and thermal resistance values are shown for a single device (During dual operation, power is evenly applied to both devices.)

Note 4:
$$V_{DD} = -16 \text{ V}$$
, $T_{ch} = 25^{\circ}\text{C}$, $L = 1.0 \text{ mH}$, $I_{AR} = -5 \text{ A}$, $R_G = 25 \Omega$

Note 5: Repetitive rating: pulse width limited by max channel temperature

Note 6: \circ on lower right of the marking indicates Pin 1.

* shows lot number. (year of manufacture: last decimal digit of the year of manufacture, month of manufacture: January to December are denoted by letters A to L respectively.)

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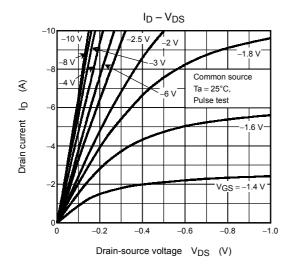
Electrical Characteristics (Ta = 25°C)

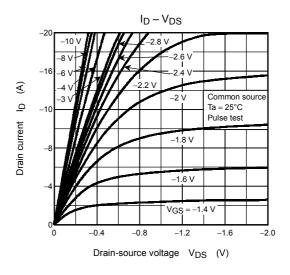
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cui	rrent	I _{GSS}	$V_{GS} = \pm 10 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μΑ
Drain cut-OFF cu	ırrent	I _{DSS}	$V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}$	_	<u> </u>		μА
Drain-source hre	akdown voltage	V _{(BR)DSS}	$I_D = -10 \text{ mA}, V_{GS} = 0 \text{ V}$	-20	_		V
Brain-source bre	andown voltage	V _{(BR)DSX}	$I_D = -10 \text{ mA}, V_{GS} = 12 \text{ V}$		V		
Gate threshold ve	oltage	V _{th}	$V_{DS} = -10 \text{ V}, I_D = -200 \mu\text{A}$	-0.5	_	-1.2	V
			$V_{GS} = -2.0 \text{ V}, I_D = -2.5 \text{ A}$	_	42	95	
Drain-source ON resistance		R _{DS} (ON)	$V_{GS} = -2.5 \text{ V}, I_D = -2.5 \text{ A}$	_	32	60	mΩ
			$V_{GS} = -4.5 \text{ V}, I_D = -2.5 \text{ A}$	_	22	35	
Forward transfer	admittance	Y _{fs}	$V_{DS} = -10 \text{ V}, I_D = -2.5 \text{ A}$	5.5	12	_	S
Input capacitance		C _{iss}	V _{DS} = -10 V, V _{GS} = 0 V, f = 1 MHz	_	1590	_	pF
Reverse transfer capacitance		C _{rss}		_	380	_	
Output capacitance		C _{oss}		_	430	_	
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Rise time	t _r	0 V ¬ r In=-2.5 A	_	9		
	16		ns				
	Fall time	t _f	1	_	45		115
	Turn-OFF time	t _{off}		_	113	1	
		Qg		_	28.5		
Gate-source charge 1		Q _{gs}	$V_{DD} \approx 16 \text{ V}, V_{GS} = -5 \text{ V}, I_D = -5 \text{ A}$	_	19	_	nC -
Gate-drain ("miller") charge		Q _{gd}		_	9.4		

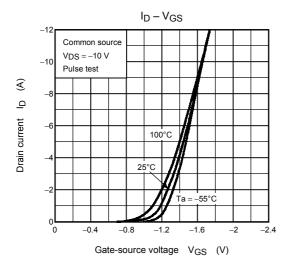
Source-Drain Ratings and Characteristics (Ta = 25°C)

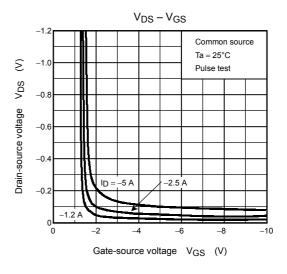
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I _{DRP}	_	_	_	-20	Α
Forward voltage (diode)		V_{DSF}	$I_{DR} = -5 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	1.2	V

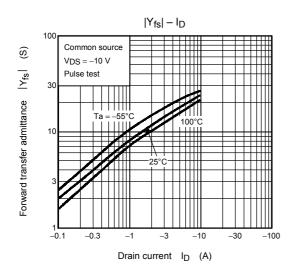
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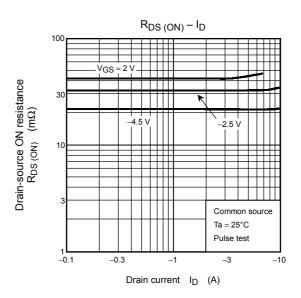




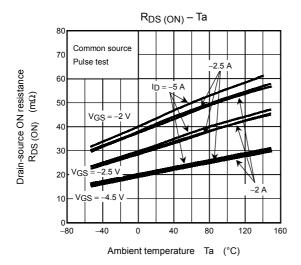


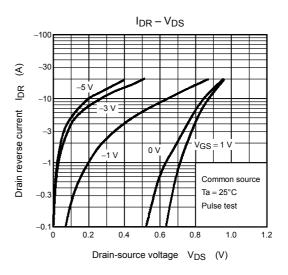


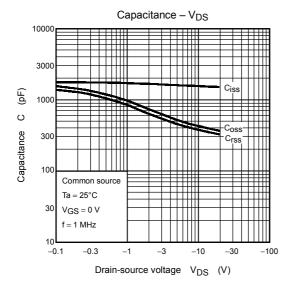


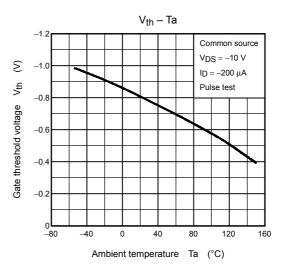


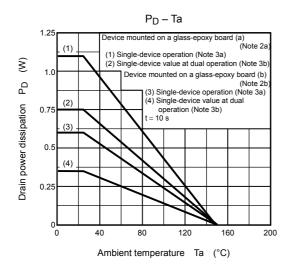
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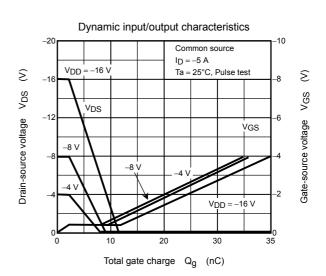


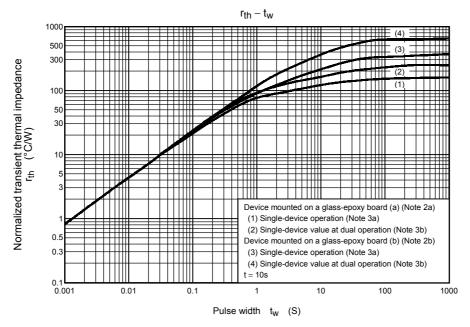




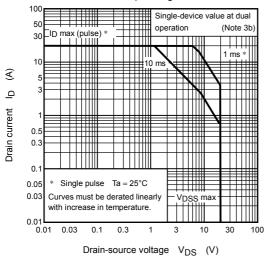












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